

December 1992

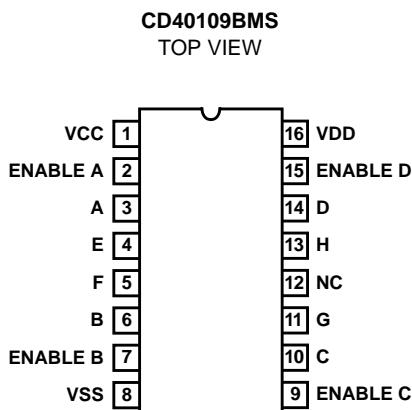
CMOS Quad Low-to-High Voltage Level Shifter

Features

- High Voltage Type (20V Rating)
- Independence of Power Supply Sequence Considerations
 - VCC can Exceed VDD
 - Input Signals can Exceed Both VCC and VDD
- Up and Down Level Shifting Capability
- Three-State Outputs with Separate Enable Controls
- 100% Tested for Quiescent Current at 20V
- 5V, 10V and 15V Parametric Ratings
- Maximum Input Current of $1\mu A$ at 18V Over Full Package Temperature Range; $100nA$ at 18V and $+25^\circ C$
- Noise Margin (Over Full Package/Temperature Range)
 - 1V at $VCC = 5V$, $VDD = 10V$
 - 2V at $VCC = 10V$, $VDD = 15V$
- Standardized Symmetrical Output Characteristics
- Meets All Requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications

- High or Low Level Shifting with Three-State Outputs for Unidirectional or Bidirectional Bussing
- Isolation of Logic Subsystems Using Separate Power Supplies from Supply Sequencing, Supply Loss and Supply Regulation Considerations

Pinout**Description**

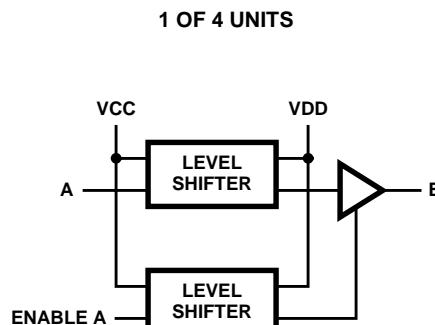
CD40109BMS contains four low-to-high voltage level shifting circuits. Each circuit will shift a low voltage digital logic input signal (A, B, C, D) with logical 1 = VCC and logical 0 = VSS to a higher voltage output signal (E, F, G, H) with logical 1 = VDD and logical 0 = VSS.

The CD40109BMS, unlike other low-to-high level shifting circuits, does not require the presence of the high voltage supply (VDD) before the application of either the low voltage supply (VCC) or the input signals. There are no restrictions on the sequence of application of VDD, VCC, or the input signals. In addition, with one exception there are no restrictions on the relative magnitudes of the supply voltages or input signals within the device maximum ratings, provided that the input signal swings between VSS and at least 0.7VCC; VCC may exceed VDD, and input signals may exceed VCC and VDD. When operated in the mode $VCC > VDD$, the CD40109BMS will operate as a high-to-low level shifter.

The CD40109BMS also features individual three-state output capability. A low level on any of the separately enabled three-state output controls produces a high impedance state in the corresponding output.

The CD40109BMS is supplied in these 16-lead outline packages:

Braze Seal DIP	H4T
Frit Seal DIP	H1E
Ceramic Flatpack	H6W

Functional Diagram

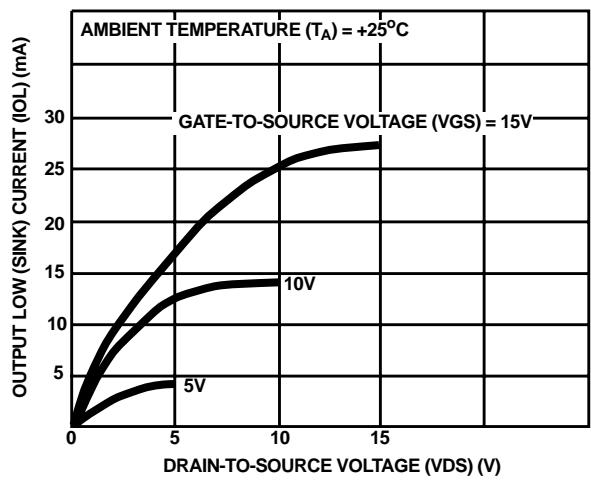
Typical Performance Characteristics

FIGURE 2. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

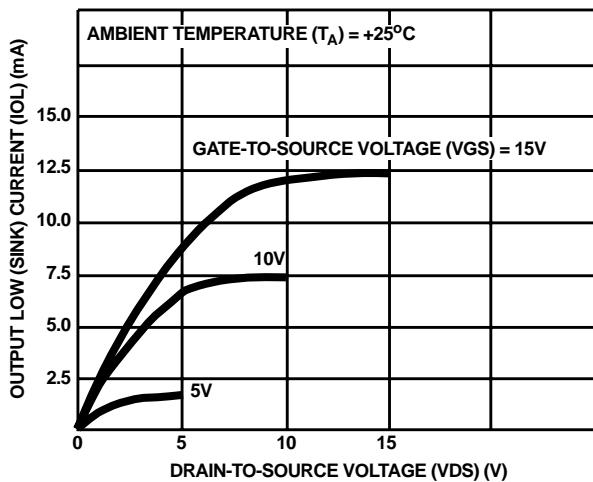


FIGURE 3. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

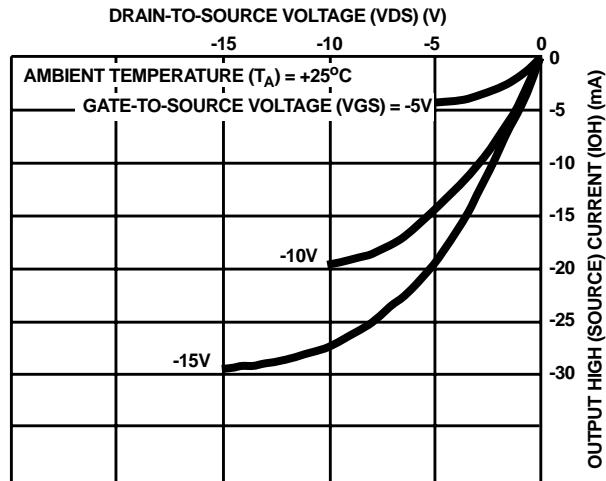


FIGURE 4. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

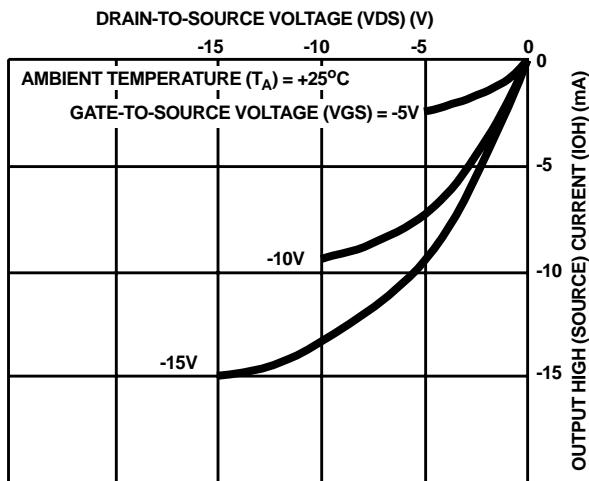


FIGURE 5. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

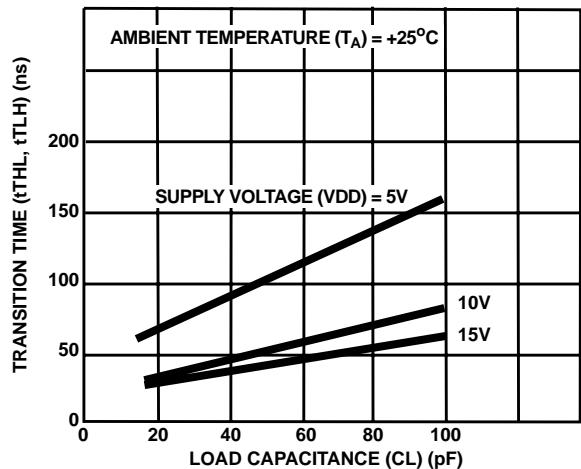


FIGURE 6. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE

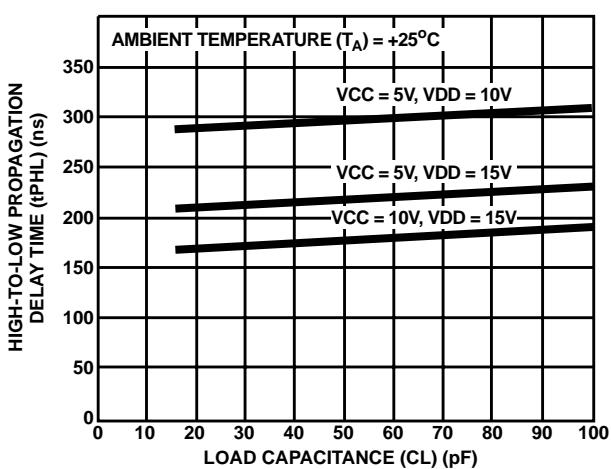


FIGURE 7. TYPICAL HIGH-TO-LOW PROPAGATION DELAY TIME AS A FUNCTION OF LOAD CAPACITANCE

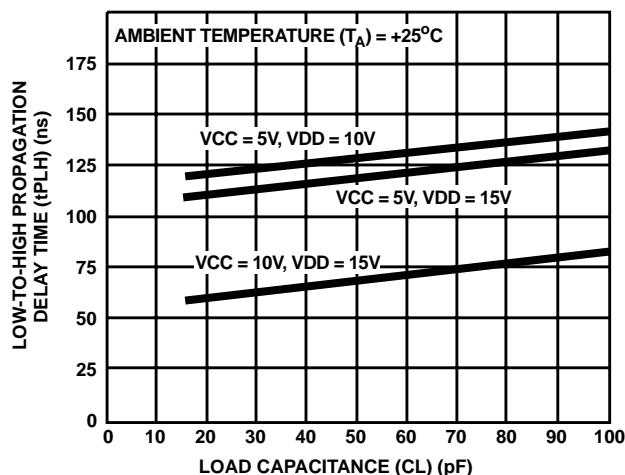
Typical Performance Characteristics (Continued)

FIGURE 8. TYPICAL LOW-TO-HIGH PROPAGATION DELAY TIME AS A FUNCTION OF LOAD CAPACITANCE

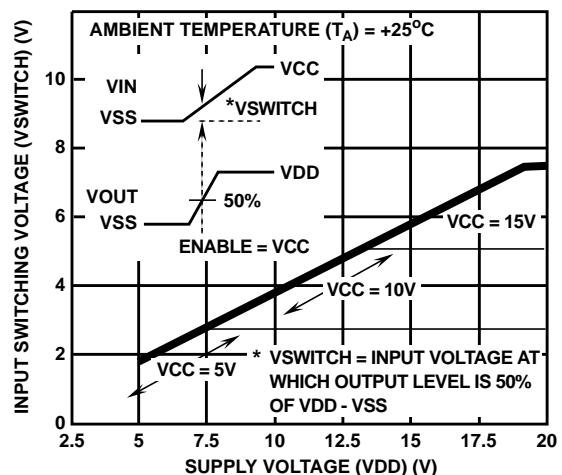


FIGURE 9. TYPICAL INPUT SWITCHING AS A FUNCTION OF HIGH LEVEL SUPPLY VOLTAGE

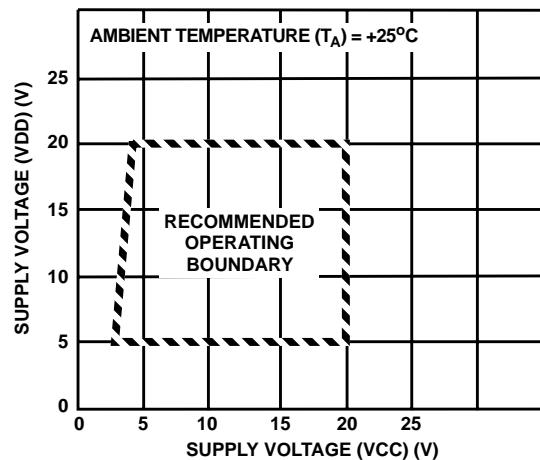


FIGURE 10. HIGH LEVEL SUPPLY VOLTAGE vs LOW LEVEL SUPPLY VOLTAGE

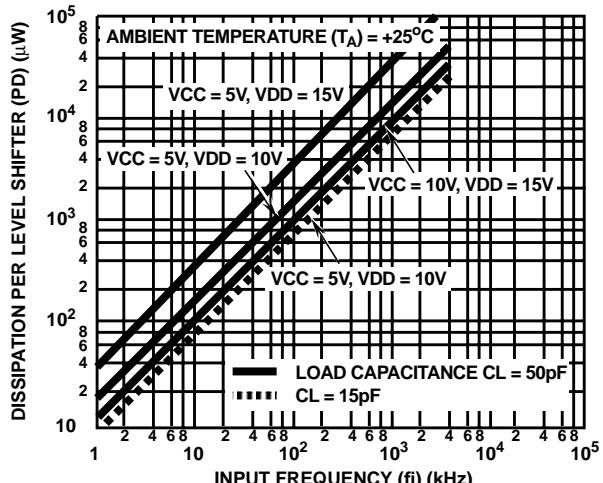
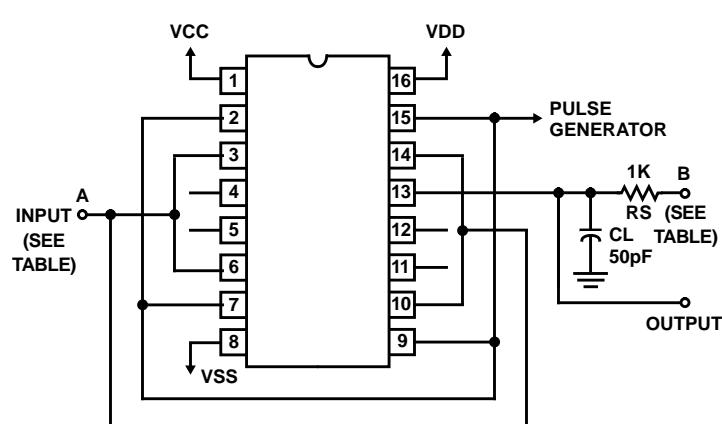


FIGURE 11. TYPICAL DYNAMIC POWER DISSIPATION AS A FUNCTION OF INPUT FREQUENCY

Test Circuit and Waveform



CHAR	TEST VOLTAGE	
	AT A	AT B
tPHZ	VCC	VSS
tPLZ	VSS	VDD
tPZL	VSS	VDD
tPZH	VCC	VSS

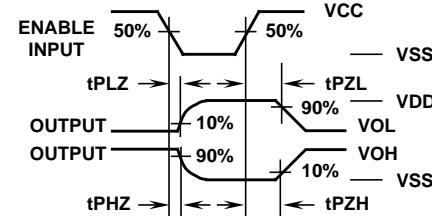
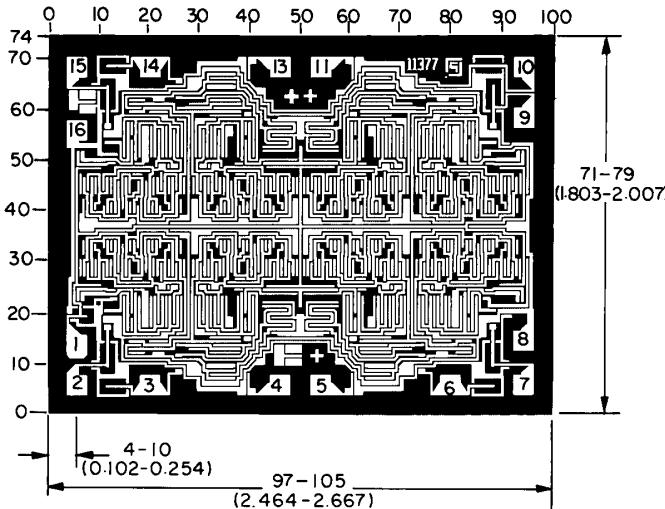


FIGURE 12. OUTPUT ENABLE DELAY TIMES TEST CIRCUIT AND WAVEFORMS

Chip Dimensions and Pad Layout

Dimensions in parenthesis are in millimeters and are derived from the basic inch dimensions as indicated.
Grid graduations are in mils (10^{-3} inch).

METALLIZATION: Thickness: 11kÅ – 14kÅ, AL.

PASSIVATION: 10.4kÅ - 15.6kÅ, Silane

BOND PADS: 0.004 inches X 0.004 inches MIN

DIE THICKNESS: 0.0198 inches - 0.0218 inches

All Intersil semiconductor products are manufactured, assembled and tested under **ISO9000** quality systems certification.

Intersil products are sold by description only. Intersil Corporation reserves the right to make changes in circuit design and/or specifications at any time without notice. Accordingly, the reader is cautioned to verify that data sheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.

For information regarding Intersil Corporation and its products, see web site <http://www.intersil.com>

Sales Office Headquarters**NORTH AMERICA**

Intersil Corporation
P. O. Box 883, Mail Stop 53-204
Melbourne, FL 32902
TEL: (321) 724-7000
FAX: (321) 724-7240

EUROPE

Intersil SA
Mercure Center
100, Rue de la Fusée
1130 Brussels, Belgium
TEL: (32) 2.724.2111
FAX: (32) 2.724.22.05

ASIA

Intersil (Taiwan) Ltd.
Taiwan Limited
7F-6, No. 101 Fu Hsing North Road
Taipei, Taiwan
Republic of China
TEL: (886) 2 2716 9310
FAX: (886) 2 2715 3029